



—Interlayer bonding—
Bonding sheet **“A series”**

Example of use

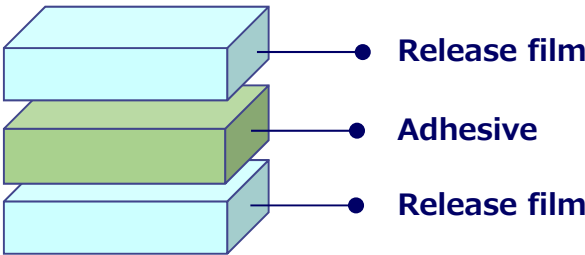
- Smartphone
- Tablet PC
- Laptop computer



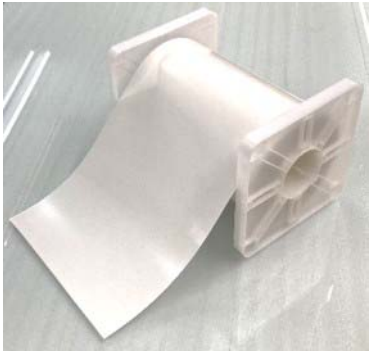
Characteristics

- Excellent adhesion and insulation resistance.
- Various bonding sheets are available for Multi-layer FPC and stiffener bonding.

Product structure



■ Appearance



Product Properties

UL 94 Flammability* : registered in combination with PI film or Arisawa FCCL.

Item	Unit	AU	AED S	A11F	AE15	AE91
Characteristic	—	For general purpose	Interlayer insulation (Low elasticity)	Interlayer insulation (High solder-heat resistance)	Interlayer insulation (Applicable on fine pattern)	Interlayer insulation (Flame retardant, workable with quick-press)
Peel strength (Peel 1mil/1oz FCCL)	N/cm	24	12	13	15	21
Solder heat resistance	℃	300	288	320	288	288
Elastic modulus	GPa	0.6	0.2	2.2	1.4	1.1
Time to gap filling by quick-press	Sec.	120	180	180	120	60
UL 94 Flammability*	—	VTM-0	V-0	VTM-0	VTM-0	Equivalent to V-0
Tg	℃	65	-6 & 114	81	56	74
Remarks	—	Low cost	UL approved	Withstand 260℃ solder heat resistance after 96hr/40℃/90%	Ion migration resistance (L/S=20/20) 85℃/85%/50V/1000hr	Ion migration resistance (L/S=20/20) 85℃/85%/50V/1000hr

Sample making conditions (Pressing) : 160℃×3MPa×60min



Sales & Marketing Department
Tokyo Head Office: Yanagibashi 2-12-5, Taito-ku, Tokyo 111-0052, Japan Tel : +81-3-3861-1110
Kansai: Tsumori 3-7-27, Nishinari-ku, Osaka 557-0062, Japan Tel : +81-6-4703-3168

The data in this document are measured values, not for guaranteed.